



Receipt

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

**COPY OF PAPERS  
ORIGINALLY FILED**

TAGUCHI ET AL

Serial No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE  
FOR REFLOW SOLDERING

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Assistant Commissioner for Patents  
Washington, D.C. 20231

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FEB 13 2002

Dear Sir:

**TC 1700**

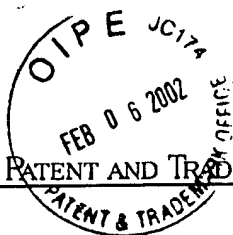
An error has been noted on the Official Filing Receipt in the referenced application, namely, the name of the first inventor is misspelled. Please issue a Corrected Official Filing Receipt correcting this error as marked in red on the attached copy of the Official Filing Receipt.

Respectfully submitted,

*Michael Tobias*

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Date: Feb 5, 2002  
1023



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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTY. DOCKET NO	DRAWINGS	TOT CLAIMS	IND CLAIMS
09/642,765	08/22/2000	1725	840	1023/HIROSE		12	1

**CONFIRMATION NO. 8065**

27649  
MICHAEL TOBIAS  
1730 K ST NW  
SUITE 304  
WASHINGTON, DC 20006

**CORRECTED FILING RECEIPT**



\*OC00000005924857\*

Date Mailed: 04/02/2001

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. **If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the PTO processes the reply to the Notice, the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).**

**Applicant(s)**

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Domestic Priority data as claimed by applicant

Foreign Applications

If Required, Foreign Filing License Granted 10/11/2000

Projected Publication Date: N/A

Non-Publication Request: No

Early Publication Request: No

**Title**

Lead-free solder paste for reflow soldering

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**TC 1700**

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**CONFIRMATION NO. 8065**


Bib Data Sheet

<b>SERIAL NUMBER</b> 09/642,765	<b>FILING DATE</b> 08/22/2000 <b>RULE</b>	<b>CLASS</b> 228	<b>GROUP ART UNIT</b> 1725	<b>ATTORNEY DOCKET NO.</b> 1023/HIROSE
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**APPLICANTS**
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 Ryoichi Suzuki, Saratoga, CA;  
 Tetsuya Okuno, San Jose, CA;
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\*\* CONTINUING DATA \*\*\*\*\*

\*\* FOREIGN APPLICATIONS \*\*\*\*\*

**IF REQUIRED, FOREIGN FILING LICENSE GRANTED**

\*\* 10/11/2000

Foreign Priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no	STATE OR COUNTRY JAPAN	SHEETS DRAWING	TOTAL CLAIMS 12	INDEPENDENT CLAIMS 1
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after Allowance				
Verified and Acknowledged Examiner's Signature _____ Initials _____				

**ADDRESS**

27649

**TITLE**

Lead-free solder paste for reflow soldering

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